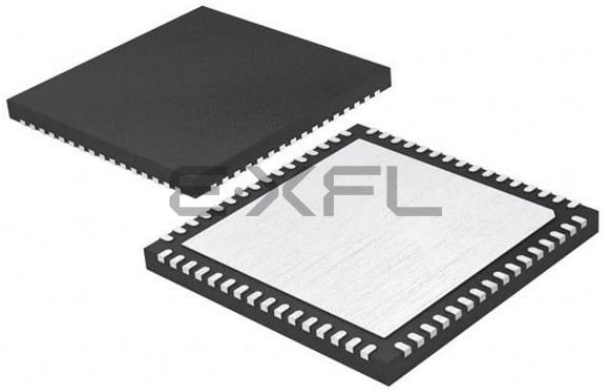
Microchip Technology - PIC32MX320F064HT-40I/MR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

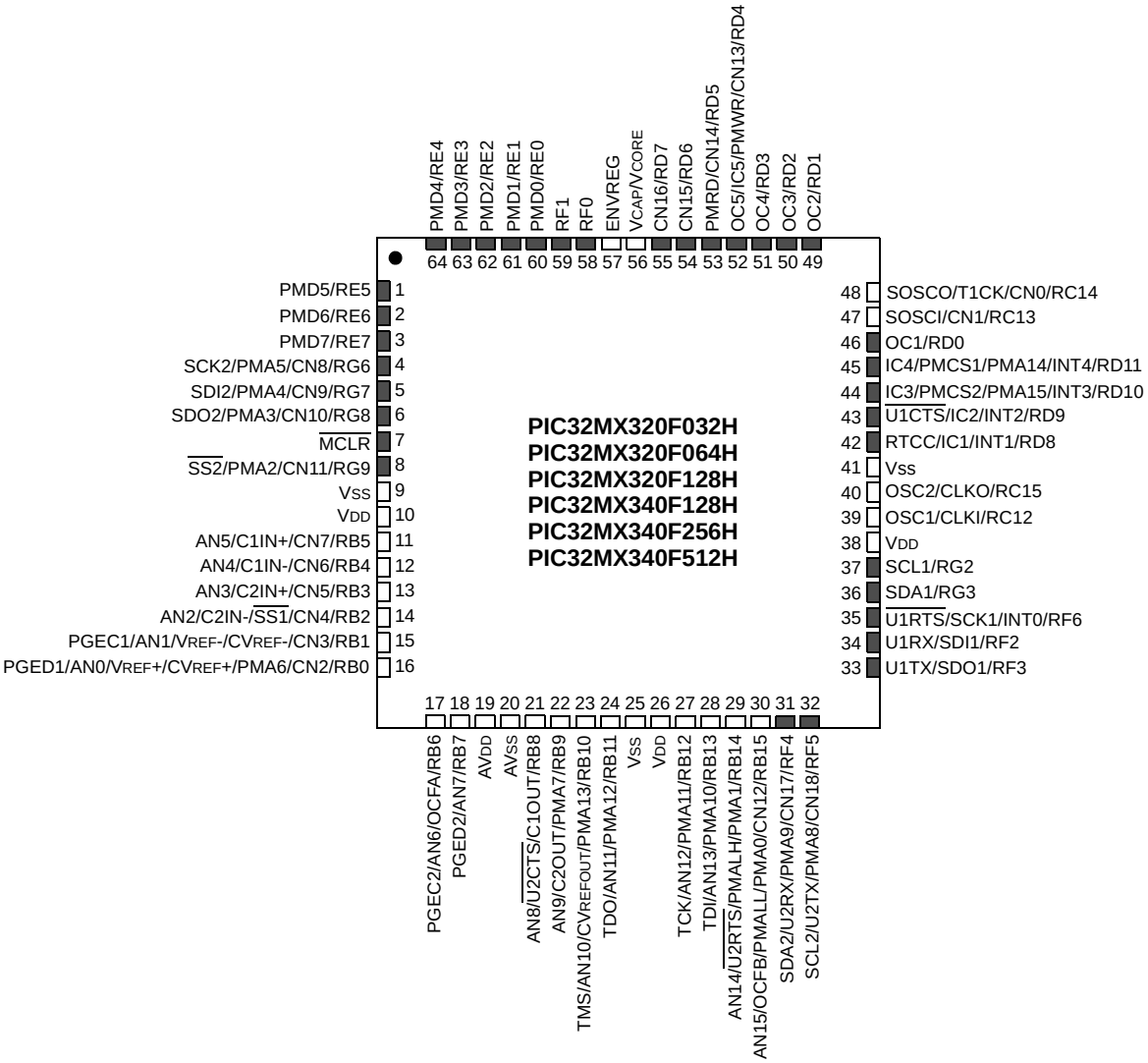
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx320f064ht-40i-mr

Pin Diagrams

64-Pin QFN (General Purpose)

■ = Pins are up to 5V tolerant



Note: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternately, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 2, MPLAB ICD 3 or MPLAB REAL ICE™.

For more information on ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"MPLAB® ICD 2 In-Circuit Debugger User's Guide"* DS51331
- *"Using MPLAB® ICD 2"* (poster) DS51265
- *"MPLAB® ICD 2 Design Advisory"* DS51566
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™"* (poster) DS51749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternately, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

The trace pins can be connected to a hardware-trace-enabled programmer to provide a compress real time instruction trace. When used for trace the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

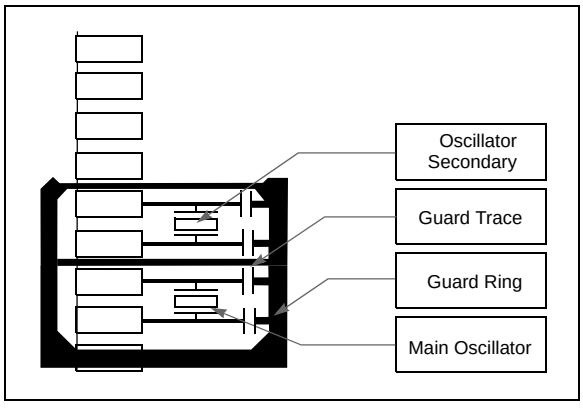


TABLE 3-1: MIPS® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
MULT/MULTU, MADD/MADDU, MSUB/MSUBU	16 bits	1	1
	32 bits	2	2
MUL	16 bits	2	1
	32 bits	3	2
DIV/DIVU	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

The MIPS architecture defines that the result of a multiply or divide operation be placed in the HI and LO registers. Using the Move-From-HI (MFHI) and Move-From-LO (MFLO) instructions, these values can be transferred to the general purpose register file.

In addition to the HI/LO targeted operations, the MIPS32 architecture also defines a multiply instruction, MUL, which places the least significant results in the primary register file instead of the HI/LO register pair. By avoiding the explicit MFLO instruction, required when using the LO register, and by supporting multiple destination registers, the throughput of multiply-intensive operations is increased.

Two other instructions, multiply-add (MADD) and multiply-subtract (MSUB), are used to perform the multiply-accumulate and multiply-subtract operations. The MADD instruction multiplies two numbers and then adds the product to the current contents of the HI and LO registers. Similarly, the MSUB instruction multiplies two operands and then subtracts the product from the HI and LO registers. The MADD and MSUB operations are commonly used in DSP algorithms.

3.2.3 SYSTEM CONTROL COPROCESSOR (CP0)

In the MIPS architecture, CP0 is responsible for the virtual-to-physical address translation, the exception control system, the processor's diagnostics capability, the operating modes (kernel, user and debug), and whether interrupts are enabled or disabled. Configuration information, such as presence of options like MIPS16e, is also available by accessing the CP0 registers, listed in Table 3-2.

TABLE 3-2: COPROCESSOR 0 REGISTERS

Register Number	Register Name	Function
0-6	Reserved	Reserved
7	HWREna	Enables access via the RDHWR instruction to selected hardware registers
8	BadVAddr(1)	Reports the address for the most recent address-related exception
9	Count(1)	Processor cycle count
10	Reserved	Reserved
11	Compare(1)	Timer interrupt control
12	Status(1)	Processor status and control
12	IntCtl(1)	Interrupt system status and control
12	SRSCtl(1)	Shadow register set status and control
12	SRSMap(1)	Provides mapping from vectored interrupt to a shadow set
13	Cause(1)	Cause of last general exception
14	EPC(1)	Program counter at last exception
15	PRId	Processor identification and revision
15	EBASE	Exception vector base register
16	Config	Configuration register
16	Config1	Configuration register 1
16	Config2	Configuration register 2
16	Config3	Configuration register 3

TABLE 4-6: INTERRUPT REGISTERS MAP FOR THE PIC32MX420F032H DEVICE ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-19: FLASH CONTROLLER REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F400	NVMCON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	—	NVMOP<3:0>				0000
F410	NVMKEY	31:16	NVMKEY<31:0>																0000
		15:0																	0000
F420	NVMADDR(1)	31:16	NVMADDR<31:0>																0000
		15:0																	0000
F430	NVMDATA	31:16	NVMDATA<31:0>																0000
		15:0																	0000
F440	NVMSRC ADDR	31:16	NVMSRCADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

TABLE 4-20: SYSTEM CONTROL REGISTERS MAP(1,2)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F000	OSCCON	31:16	—	—	PLLODIV<2:0>			FRCDIV<2:0>			—	SOSCRDY	—	PBDIV<1:0>		PLLMULT<2:0>			0000
		15:0	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	ULOCK	SLOCK	SLPEN	CF	UFRCEN	SOSCEN	OSWEN	0000
F010	OSCTUN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000
0000	WDTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	SWDTPS<4:0>					—	WDTCLR	0000
F600	RCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CMR	VREGS	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR	POR	0000
F610	RSWRST	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SWRST	0000
F230	SYSKEY(3)	31:16	SYSKEY<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

3: This register does not have associated CLR, SET, and INV registers.

NOTES:

10.0 DIRECT MEMORY ACCESS (DMA) CONTROLLER

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 31. "Direct Memory Access (DMA) Controller"** (DS61117) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

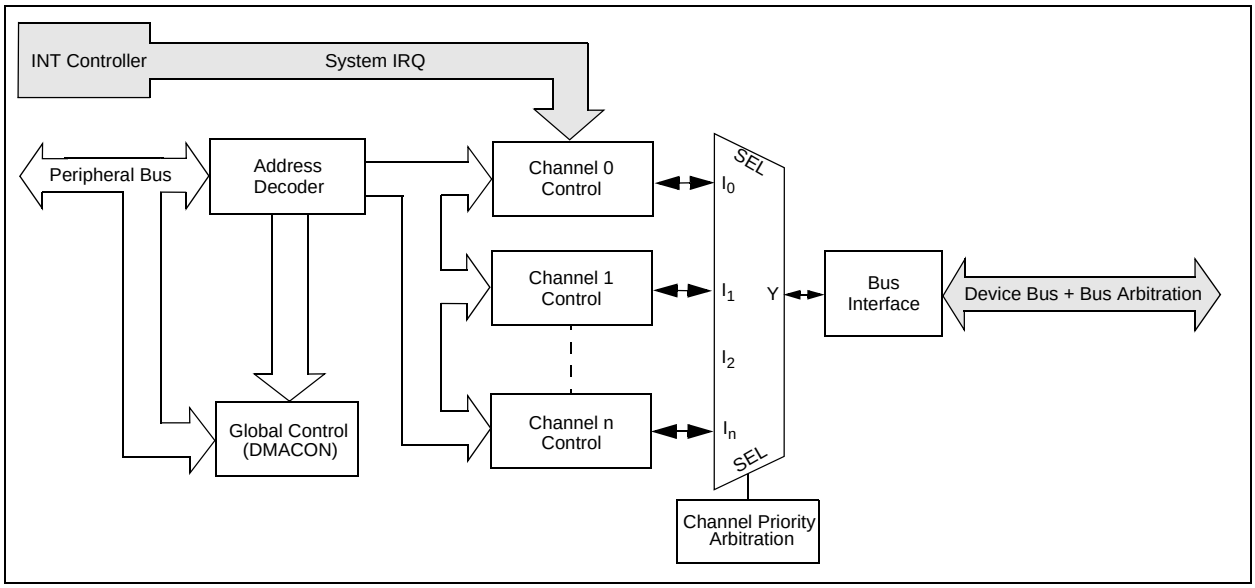
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC32MX Direct Memory Access (DMA) controller is a bus master module useful for data transfers between different devices without CPU intervention. The source and destination of a DMA transfer can be any of the memory mapped modules existent in the PIC32MX (such as Peripheral Bus (PBUS) devices: SPI, UART, PMP, and so on) or memory itself.

Following are some of the key features of the DMA controller module:

- Four Identical Channels, each featuring:
  - Auto-Increment Source and Destination Address Registers
  - Source and Destination Pointers
  - Memory to Memory and Memory to Peripheral Transfers
- Automatic Word-Size Detection:
  - Transfer Granularity, down to byte level
  - Bytes need not be word-aligned at source and destination
- Fixed Priority Channel Arbitration
- Flexible DMA Channel Operating Modes:
  - Manual (software) or automatic (interrupt) DMA requests
  - One-Shot or Auto-Repeat Block Transfer modes
  - Channel-to-channel chaining
- Flexible DMA Requests:
  - A DMA request can be selected from any of the peripheral interrupt sources
  - Each channel can select any (appropriate) observable interrupt as its DMA request source
  - A DMA transfer abort can be selected from any of the peripheral interrupt sources
  - Pattern (data) match transfer termination
- Multiple DMA Channel Status Interrupts:
  - DMA channel block transfer complete
  - Source empty or half empty
  - Destination full or half-full
  - DMA transfer aborted due to an external event
  - Invalid DMA address generated
- DMA Debug Support Features:
  - Most recent address accessed by a DMA channel
  - Most recent DMA channel to transfer data
- CRC Generation Module:
  - CRC module can be assigned to any of the available channels
  - CRC module is highly configurable

FIGURE 10-1: DMA BLOCK DIAGRAM



23.0 COMPARATOR

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to **Section 19. "Comparator"** (DS61110) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

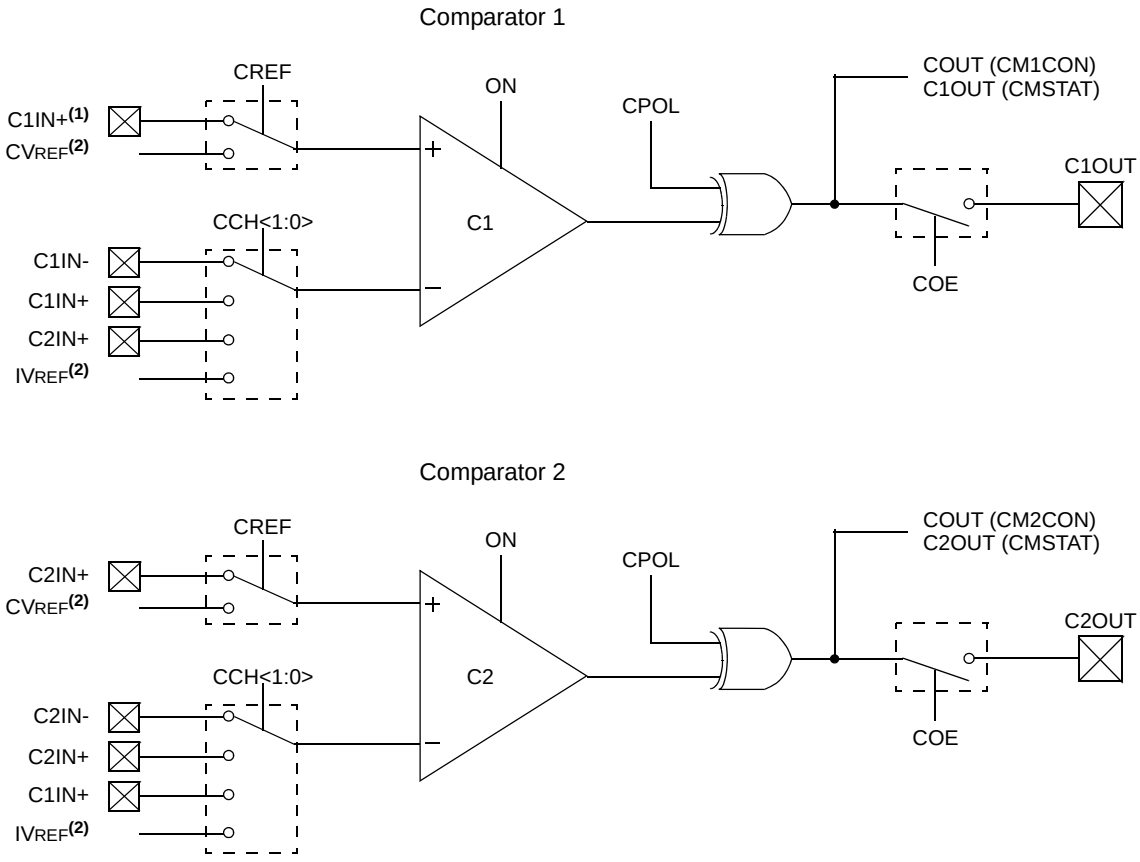
The PIC32MX3XX/4XX Analog Comparator module contains one or more comparator(s) that can be configured in a variety of ways.

Following are some of the key features of this module:

- Selectable inputs available include:
  - Analog inputs multiplexed with I/O pins
  - On-chip internal absolute voltage reference (IV_{REF})
  - Comparator voltage reference (CV_{REF})
- Outputs can be inverted
- Selectable interrupt generation

A block diagram of the comparator module is illustrated in Figure 23-1.

FIGURE 23-1: COMPARATOR BLOCK DIAGRAM



Note 1: On USB variants, when USB is enabled, this pin is controlled by the USB module and therefore is not available as a comparator input.

2: Internally connected.

26.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX3XX/4XX family family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-up Timer"** (DS61114), **Section 32. "Configuration"** (DS61124) and **Section 33. "Programming and Diagnostics"** (DS61129) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX3XX/4XX devices include several features intended to maximize application flexibility and reliability and minimize cost through elimination of external components. These are:

- Flexible Device Configuration
- Watchdog Timer
- JTAG Interface
- In-Circuit Serial Programming™ (ICSP™)

26.1 Configuration Bits

The Configuration bits can be programmed to select various device configurations.

REGISTER 26-1: DEVCFG0: DEVICE CONFIGURATION WORD 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-0	r-1	r-1	R/P	r-1	r-1	r-1	R/P
	—	—	—	CP	—	—	—	BWP
23:16	r-1	r-1	r-1	r-1	R/P	R/P	R/P	R/P
	—	—	—	—	PWP<7:4>			
15:8	R/P	R/P	R/P	R/P	r-1	r-1	r-1	r-1
	PWP<3:0>				—	—	—	—
7:0	r-1	r-1	r-1	r-1	R/P	r-1	R/P	R/P
	—	—	—	—	ICESEL	—	DEBUG<1:0>	

Legend:			
R = Readable bit	W = Writable bit	P = Programmable bit	r = Reserved bit
U = Unimplemented bit	-n = Bit Value at POR: ('0', '1', x = Unknown)		

bit 31 **Reserved:** Write '0'

bit 30-29 **Reserved:** Write '1'

bit 28 **CP:** Code-Protect bit

Prevents boot and program Flash memory from being read or modified by an external programming device.
1 = Protection disabled
0 = Protection enabled

bit 27-25 **Reserved:** Write '1'

bit 24 **BWP:** Boot Flash Write-Protect bit

Prevents boot Flash memory from being modified during code execution.
1 = Boot Flash is writable
0 = Boot Flash is not writable

bit 23-20 **Reserved:** Write '1'

REGISTER 26-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	R/P	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	—	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:			
R = Readable bit	W = Writable bit	P = Programmable bit	r = Reserved bit
U = Unimplemented bit	-n = Bit Value at POR: (‘0’, ‘1’, x = Unknown)		

bit 31-24 **Reserved:** Write ‘1’

bit 23 **FWDTEN:** Watchdog Timer Enable bit
1 = The WDT is enabled and cannot be disabled by software
0 = The WDT is not enabled; it can be enabled in software

bit 22-21 **Reserved:** Write ‘1’

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits
10100 = 1:1048576
10011 = 1:524288
10010 = 1:262144
10001 = 1:131072
10000 = 1:65536
01111 = 1:32768
01110 = 1:16384
01101 = 1:8192
01100 = 1:4096
01011 = 1:2048
01010 = 1:1024
01001 = 1:512
01000 = 1:256
00111 = 1:128
00110 = 1:64
00101 = 1:32
00100 = 1:16
00011 = 1:8
00010 = 1:4
00001 = 1:2
00000 = 1:1
All other combinations not shown result in operation = ‘10100’

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits
1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

Note 1: Do not disable POSC (POSCMOD = 00) when using this oscillator source.

26.3 On-Chip Voltage Regulator

All PIC32MX3XX/4XX device's core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX3XX/4XX incorporate an on-chip regulator providing the required core logic voltage from VDD.

The internal 1.8V regulator is controlled by the ENVREG pin. Tying this pin to VDD enables the regulator, which in turn provides power to the core. A low ESR capacitor (such as tantalum) must be connected to the VCORE/VCAP pin (Figure 26-2). This helps to maintain the stability of the regulator. The recommended value for the filer capacitor is provided in **Section 29.1 "DC Characteristics"**.

Note:	It is important that the low ESR capacitor is placed as close as possible to the VCORE/VCAP pin.

Tying the ENVREG pin to VSS disables the regulator. In this case, separate power for the core logic at a nominal 1.8V must be supplied to the device on the VCORE/VCAP pin.

Alternatively, the VCORE/VCAP and VDD pins can be tied together to operate at a lower nominal voltage. Refer to Figure 26-2 for possible configurations.

26.3.1 ON-CHIP REGULATOR AND POR

When the voltage regulator is enabled, it takes fixed delay for it to generate output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

If the regulator is disabled, a separate Power-up Timer (PWRT) is automatically enabled. The PWRT adds a fixed delay of TPWRT at device start-up. See **Section 29.0 "Electrical Characteristics"** for more information on TPU AND TPWRT.

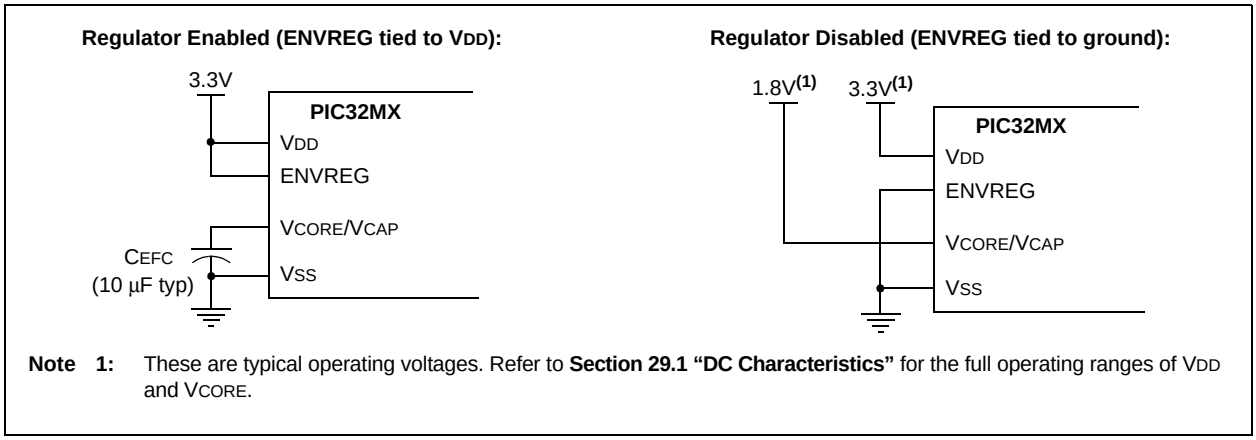
26.3.2 ON-CHIP REGULATOR AND BOR

When the on-chip regulator is enabled, PIC32MX3XX/4XX devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in **Section 29.1 "DC Characteristics"**.

26.3.3 POWER-UP REQUIREMENTS

The on-chip regulator is designed to meet the power-up requirements for the device. If the application does not use the regulator, then strict power-up conditions must be adhered to. While powering up, VCORE must never exceed VDD by 0.3 volts.

FIGURE 26-2: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 29.1 "DC Characteristics"** for the full operating ranges of VDD and VCORE.

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
JAL	Jump and Link	GPR[31] = PC + 8 PC = PC[31:28] || offset<<2
JALR	Jump and Link Register	Rd = PC + 8 PC = Rs
JALR.HB	Jump and Link Register with Hazard Barrier	Like JALR, but also clears execution and instruction hazards
JR	Jump Register	PC = Rs
JR.HB	Jump Register with Hazard Barrier	Like JR, but also clears execution and instruction hazards
LB	Load Byte	Rt = (byte)Mem[Rs+offset]
LBU	Unsigned Load Byte	Rt = (ubyte))Mem[Rs+offset]
LH	Load Halfword	Rt = (half)Mem[Rs+offset]
LHU	Unsigned Load Halfword	Rt = (uhalf)Mem[Rs+offset]
LL	Load Linked Word	Rt = Mem[Rs+offset> LL_{bit} = 1 LLAdr = Rs + offset
LUI	Load Upper Immediate	Rt = immediate << 16
LW	Load Word	Rt = Mem[Rs+offset]
LWPC	Load Word, PC relative	Rt = Mem[PC+offset]
LWL	Load Word Left	Re = Re MERGE Mem[Rs+offset]
LWR	Load Word Right	Re = Re MERGE Mem[Rs+offset]
MADD	Multiply-Add	HI | LO += (int)Rs * (int)Rt
MADDU	Multiply-Add Unsigned	HI | LO += (uns)Rs * (uns)Rt
MFC0	Move from Coprocessor 0	Rt = CPR[0, Rd, sel]
MFHI	Move from HI	Rd = HI
MFLO	Move from LO	Rd = LO
MOVN	Move Conditional on Not Zero	if Rt ¼ 0 then Rd = Rs
MOVZ	Move Conditional on Zero	if Rt = 0 then Rd = Rs
MSUB	Multiply-Subtract	HI | LO -= (int)Rs * (int)Rt
MSUBU	Multiply-Subtract Unsigned	HI | LO -= (uns)Rs * (uns)Rt
MTC0	Move to Coprocessor 0	CPR[0, n, Sel] = Rt
MTHI	Move to HI	HI = Rs
MTLO	Move to LO	LO = Rs
MUL	Multiply with register write	HI | LO =Unpredictable Rd = ((int)Rs * (int)Rt)$_{31..0}$
MULT	Integer Multiply	HI | LO = (int)Rs * (int)Rd
MULTU	Unsigned Multiply	HI | LO = (uns)Rs * (uns)Rd
NOP	No Operation (Assembler idiom for: SLL r0, r0, r0)	
NOR	Logical NOR	Rd = ~(Rs | Rt)
OR	Logical OR	Rd = Rs | Rt
ORI	Logical OR Immediate	Rt = Rs | Immed
RDHWR	Read Hardware Register (if enabled by $HWRE_{na}$ Register)	Re = HWR[Rd]

Note 1: This instruction is deprecated and should not be used.

28.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

28.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

28.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

28.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

TABLE 29-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD}) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Module Differential Current (Continued)						
DC43	—	1100	µA	-40°C	2.5V	ADC: ΔI_{ADC} **(Notes 3, 4, 6)**
DC43a	—	1100	µA	+25°C		
DC43b	—	1000	µA	+85°C		
DC43h	—	1200	µA	+105ºC		
DC43c	880	—	µA	—	—	ADC: ΔI_{ADC} **(Notes 3, 4)**
DC43e	—	1100	µA	-40°C	3.6V	ADC: ΔI_{ADC} **(Notes 3, 4)**
DC43f	—	1100	µA	+25°C		
DC43g	—	1000	µA	+85°C		
DC43i	—	1200	µA	+105ºC		

Note 1: Base I_{PD} is measured with all digital peripheral modules disabled. All I/Os are configured as inputs and pulled low. WDT and FSCM are disabled.

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: Data is characterized at +70°C and not tested. Parameter is for design guidance only.

6: This parameter is characterized, but not tested in manufacturing.

TABLE 29-13: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage	—	±7.5	±25	mV	AVDD = VDD, AVSS = VSS
D301	VICM	Input Common Mode Voltage	0	—	VDD	V	AVDD = VDD, AVSS = VSS **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max VICM = (VDD - 1)V **(Note 2)**
D303	TRESP	Response Time	—	150	400	ns	AVDD = VDD, AVSS = VSS **(Notes 1,2)**
D304	ON2OV	Comparator Enabled to Output Valid	—	—	10	µs	Comparator module is configured before setting the comparator ON bit. **(Note 2)**
D305	IVREF	Internal Voltage Reference	0.57	0.6	0.63	V	—

Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

2: These parameters are characterized but not tested.

TABLE 29-14: VOLTAGE REFERENCE SPECIFICATIONS

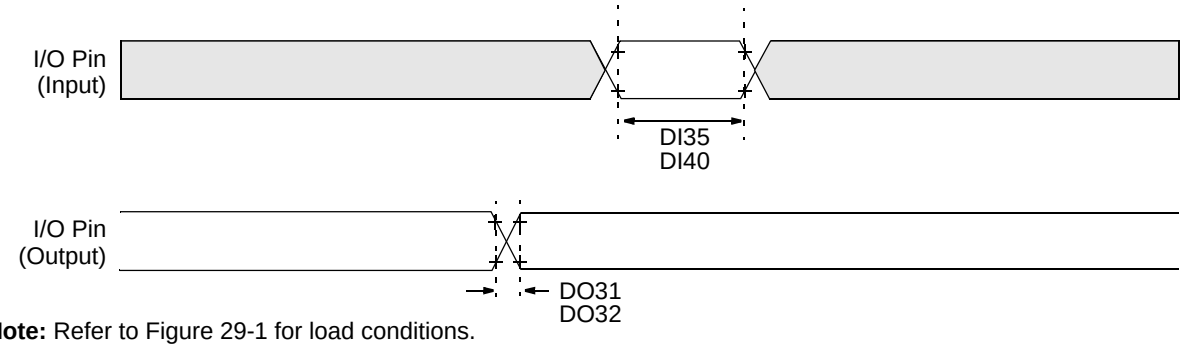
DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D310	VRES	Resolution	VDD/24	—	VDD/32	LSb	—
D311	VRAA	Absolute Accuracy	—	—	1/2	LSb	—
D312	TSET	Settling Time(1)	—	—	10	µs	—

Note 1: Settling time measured while CVRR = 1 and CVR3:CVR0 transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.

TABLE 29-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D320	VCORE	Regulator Output Voltage	1.62	1.80	1.98	V	—
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (< 1 Ohm)
D322	TPWRT	Power-up Timer Period	—	64	—	ms	ENVREG = 0

FIGURE 29-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(2)**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DO32	TIOF	Port Output Fall Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DI35	TINP	INTx Pin High or Low Time	10	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TSYSCLK	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 29-34: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD – 0.3 or 2.5	—	Lesser of VDD + 0.3 or 3.6	V	—
AD02	AVSS	Module VSS Supply	VSS	—	VSS + 0.3	V	—
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.0	—	AVDD	V	**(Note 1)**
AD05a			2.5	—	3.6	V	VREFH = AVDD **(Note 3)**
AD06	VREFL	Reference Voltage Low	AVSS	—	VREFH – 2.0	V	**(Note 1)**
AD07	VREF	Absolute Reference Voltage (VREFH – VREFL)	2.0	—	AVDD	V	**(Note 3)**
AD08	IREF	Current Drain	—	250 —	400 3	µA µA	ADC operating ADC off
Analog Input							
AD12	VINH-VINL	Full-Scale Input Span	VREFL	—	VREFH	V	—
AD13	VINL	Absolute VINL Input Voltage	AVSS – 0.3	—	AVDD/2	V	—
AD14	VIN	Absolute Input Voltage	AVSS – 0.3	—	AVDD + 0.3	V	—
AD15	—	Leakage Current	—	±0.001	±0.610	µA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V Source Impedance = 10KΩ
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	5K	Ω	**(Note 1)**
ADC Accuracy – Measurements with External VREF+/VREF-							
AD20c	Nr	Resolution	10 data bits			bits	—
AD21c	INL	Integral Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V
AD22c	DNL	Differential Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V **(Note 2)**
AD23c	GERR	Gain Error	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V
AD24n	EOFF	Offset Error	—	—	<±1	LSb	VINL = AVSS = 0V, AVDD = 3.3V
AD25c	—	Monotonicity	—	—	—	—	Guaranteed

Note 1: These parameters are not characterized or tested in manufacturing.

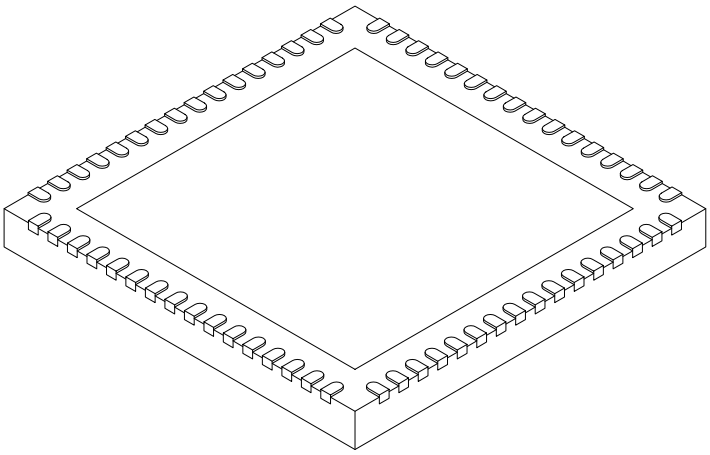
2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with 1 kHz sinewave.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 7.15 x 7.15 Exposed Pad [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		64	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	7.05	7.15	7.50
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	7.05	7.15	7.50
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

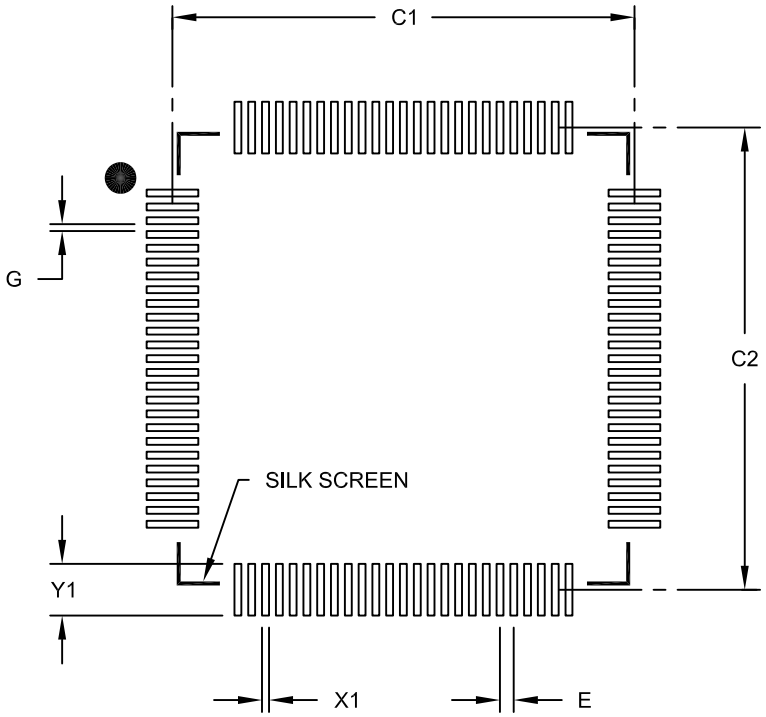
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-149C Sheet 2 of 2

100-Lead Plastic Thin Quad Flatpack (PT)-12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

APPENDIX A: REVISION HISTORY

Revision E (July 2008)

- Updated the PIC32MX340F128H features in Table 1 to include 4 programmable DMA channels.

Revision F (June 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2
- Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE
- Deleted registers in most sections, refer to the related section of the *"PIC32 Family Reference Manual"* (DS61132).

The other changes are referenced by their respective section in the following table.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, General Purpose and USB 32-bit Flash Microcontrollers"	Added a "Packages" column to Table 1 and Table 2. Corrected all pin diagrams to update the following pin names. • Changed PGC1/EMUC1 to PGEC1 • Changed PGD1/EMUD1 to PGED1 • Changed PGC2/EMUC2 to PGEC2 • Changed PGD2/EMUD2 to PGED2 Shaded appropriate pins in each diagram to indicate which pins are 5V tolerant. Added 64-Lead QFN package pin diagrams, one for General Purpose and one for USB.
Section 1.0 "Device Overview"	Reconstructed Figure 1-1 to include Timers, ADC and RTCC in the block diagram.
Section 2.0 "Guidelines for Getting Started with 32-bit Microcontrollers"	Added a new section to the data sheet that provides the following information: • Basic Connection Requirements • Capacitors • Master Clear Pin • ICSP™ Pins • External Oscillator Pins • Configuration of Analog and Digital Pins • Unused I/Os
Section 4.0 "Memory Organization"	Updated the memory maps, Figure 4-1 through Figure 4-6. All summary peripheral register maps were relocated to **Section 4.0 "Memory Organization"**.
Section 7.0 "Interrupt Controller"	Removed the "Address" column from Table 7-1.
Section 12.0 "I/O Ports"	Added a second paragraph in **Section 12.1.3 "Analog Inputs"** to clarify that all pins that share ANx functions are analog by default, because the AD1PCFG register has a default value of 0x0000.